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**DAIDO GROUP LIMITED**

**大同集團有限公司\***

*(Incorporated in Bermuda with limited liability)*

**(Stock Code: 00544)**

## **SUPPLEMENTAL AGREEMENT IN RELATION TO THE PLACING OF BONDS**

The Board announces that on 26 January 2015 (after trading hours), the Company and the Placing Agent entered into the Supplemental Agreement to amend the term of the Placing Agreement.

Reference is made to the announcement (the “**Announcement**”) of Daido Group Limited (the “**Company**”) dated 13 November 2014 in relation to, among other matters, the placing of 6% coupon unlisted bonds to be issued by the Company in an aggregate principal amount of up to HK\$500,000,000. Unless the context requires otherwise, capitalised terms used herein shall have the same meanings as those defined in the Announcement.

On 26 January 2015 (after trading hours), the Company and the Placing Agent entered into a supplemental agreement (the “**Supplemental Agreement**”), pursuant to which the Company and the Placing Agent agreed to amend the term of the Placing Agreement such that the transferability of such Bonds to be issued by the Company after the date of the Supplemental Agreement shall be subject to the prior written consent of the Company, which may or may not be granted at the absolute discretion of the Company.

*\* For identification purpose only*

As at the date of this announcement, it is noted that the Bonds in an aggregate principal amount of HK\$50,000,000 have been subscribed by the Placees and issued by the Company. For the avoidance of doubt, the Supplemental Agreement shall be effective from the date of the Supplemental Agreement until the end of the Placing Period and shall not affect, nor have any impact on, such Bonds as already subscribed by the Placees and issued by the Company before the date of the Supplemental Agreement.

The Board considers that the entering into of the Supplemental Agreement is in the interest of the Company and the Shareholders as a whole. Save and except for the aforesaid, all other terms and conditions of the Placing Agreement shall remain unchanged.

By order of the Board  
**Daido Group Limited**  
**Au Tat Wai**  
*Executive Director*

Hong Kong, 26 January 2015

As at the date of this announcement, the Board comprises executive Directors, namely, Mr. Au Tat Wai, Mr. Choy Kai Sing, Mr. Ho Hon Chung, Ivan and Mr. Tang Tsz Man, Philip; non-executive Director, namely, Mr. Fung Wa Ko; and independent non-executive Directors, namely, Mr. Fung Siu Kit, Ronny, Mr. Leung Chi Hung and Mr. Tse Yuen Ming.